

**REMARKS**

At the outset, the Examiner is thanked for the thorough review and consideration of the subject application. The Final Office Action of December 18, 2002 has been received and contents carefully reviewed.

Claims 1-17 were originally filed and remain pending. Reexamination and reconsideration of the subject application as Amended are respectfully requested.

The Examiner rejected claims 1-17 under 35 USC 103(a) as being unpatentable over Chenoweth (US Patent No. 6,076,681) in view of Hashimoto (US Patent No. 6,297,964); and rejected claims 1-17 under 35 USC 103(a) as being unpatentable over Honda (US Patent No. 4,702,370) in view of Hashimoto (US Patent No. 6,297,964). Applicants respectfully traverse these rejections.

Claim 1 is allowable at least for the reason that claim 1 recites a combination of elements including a tape carrier package part having a mounting portion for a driving integrated circuit, wherein the tape carrier package part is defined by a depression on the package film; a peripheral part for securing the tape carrier package part, said peripheral part having a plurality of sprocket holes; and a plurality of punching holes for reducing a connection between the tape carrier package part and the peripheral part.

Claim 5 is allowable at least for the reason that claim 5 recites a combination of elements including a peripheral part having sprocket holes; and a tape carrier package part defined by a depression on the package film, said tape carrier package part having a mounting portion for receiving an integrated circuit; wherein a plurality of punching holes are defined along said depression, the punching holes assisting separation of the tape carrier package part from the peripheral part.

None of the cited references, singly or in combination, teaches or suggests at least these features of the claims.

Chenoweth discloses a microchip carrier tape 10 including generally rectangular downwardly directed pockets 11, upright side walls 12, platforms 42-45 extended upwardly from bottom wall 14 to support a microchip 24 having leads 26 spaced above bottom wall 14

in groove 23, corner supports 18, 19, 21, 22 formed from material of bottom wall 14 leaving triangular openings 51-54 in wall 14, and continuous heat seals 34 and 37 securing cover tape 33 to flanges 28 and 29. See columns 3 and 4.

Honda discloses an electronic component series 100/100' including a carrier tape 30/30', a cover tape 32 bonded to the bottom surface of the carrier tape 30 sealing the bottom opening of the component storing hole to form a recess 34/34', a disc-shaped ceramic capacitor 20' having a main body 20a' and two leads 20b', an IC or similar-shaped component 40 having a main body 40a and a plurality of terminals 40b, a potentiometer 42 having a main body 42a and three terminals 42b, a substantially rectangular main body storing part 34a and two lead storing parts 34b, a cover tape 38 for sealing recess 34, and feeding holes 36.

The punching holes of the tape carrier package film according to the present invention reduce a connection between the tape carrier package part and the peripheral part (claim 1) and are defined along a depression, the punching holes assisting separation of the tape carrier package part from the peripheral part (claim 5).

The Examiner alleges that triangular openings 51-54 in Chenoweth are the punching holes recited by claims 1 and 5. As shown in the drawings of Chenoweth, and as described at column 3, lines 40-44, "Leads 26 are spaced from the adjacent side and end walls 12, 13, 16, 17 and are located above bottom wall 14 so that leads 26 do not engage any walls of the tape and therefore are not subject to forces that can bend, relocate, dislodge or break one or more leads." It appears that there is no connection between a tape carrier package part and a peripheral part in Chenoweth since the walls 12, 13, 16, 17 would prevent such a connection; and the openings 51-54 do not appear to assist in separating the tape carrier package part from the peripheral part.

The Examiner alleges that lead storing parts 34b' in Honda are the punching holes recited by claims 1 and 5. As shown in the drawings of Honda, and as described at column 4, lines 25-26, the lead storing parts 34b' "may be extended up to an edge of the carrier tape 30." It appears that there is no connection between a tape carrier package part and a peripheral part in Honda; and the lead storing parts 34b' do not appear to assist in separating the tape carrier package part from the peripheral part.

The Examiner cites Hashimoto in an attempt to cure the deficiencies of the other two references. However, Hashimoto fails to cure the deficiencies as it was merely cited for its alleged teachings of a package film.

Applicants submit that the Examiner has failed to establish a *prima facie* case of obviousness and respectfully request that the rejections under 35 USC 103(a) be withdrawn.

Moreover, claims 2-4, and 6-17 are allowable by virtue of their dependency on claims 1 and 5, which are believed to be allowable.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue.

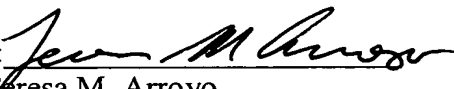
Should the Examiner deem that a telephone conference would further the prosecution of this application, the Examiner is invited to call the undersigned attorney at (202) 496-7371.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136. Please credit any overpayment to deposit Account No. 50-0911.

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Respectfully submitted,

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